

10-3004NC EPOXY ADHESIVE

DESCRIPTION:

10-3004NC is a high bond strength epoxy adhesive formulated for ease in handling and convenience for the end user. This system has a non-critical mix ratio and adjustable flexibility. 10-3004NC is also very safe to use due to the absence of harmful solvents and toxic chemicals in the formulation. 10-3004NC is a lower viscosity version of 10-3003.

10-3004NC yields high peel strength and excellent tensile strength. It also has outstanding thermal shock, impact and vibration resistance and forms excellent bonds to most substrates. This high-performance epoxy adhesive exhibits outstanding physical, thermal, and electrical insulation properties.

750 psi

TYPICAL PROPERTIES: (1:1 Ratio)

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Viscosity, cps, 25 °C	
10-3004RNC Resin	1,000
10-3004CTR Catalyst	15,000
10-3004NC Mixed	5,400
Color	Clear
Operating Temperature Range, °C	-50 to +125
Pot Life, 100-gram mass, 25 °C	30-45 minutes
Specific Gravity, 25°C	
Resin	1.16
Catalyst	0.97
Flexural Strength, psi	51,000
Izod Impact, ft-lb/in	4.0
Tensile Strength, psi	30,000
Coefficient of Thermal Expansion, ppm/°C Thermal Conductivity, W/m·°K Thermal Shock, MIL I 16923	47 0.43 Passes
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Thermal Conductivity, W/m·°K Thermal Shock, MIL I 16923 Dielectric Strength V/mil	0.43 Passes 550
Thermal Conductivity, W/m·°K Thermal Shock, MIL I 16923 Dielectric Strength V/mil Volume Resistivity, ohm-cm	0.43 Passes 550 1.1 x 10 ¹⁵
Thermal Conductivity, W/m·°K Thermal Shock, MIL I 16923 Dielectric Strength V/mil Volume Resistivity, ohm-cm Dielectric Constant 10³ cycles Dissipation Factor 10³ cycles	0.43 Passes 550 1.1 x 10 ¹⁵ 3.11
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Thermal Conductivity, W/m·°K Thermal Shock, MIL I 16923 Dielectric Strength V/mil Volume Resistivity, ohm-cm Dielectric Constant 10³ cycles Dissipation Factor 10³ cycles BOND STRENGTH: Steel to Steel	0.43 Passes 550 1.1 x 10 ¹⁵ 3.11 0.02
Thermal Conductivity, W/m·°K Thermal Shock, MIL I 16923 Dielectric Strength V/mil Volume Resistivity, ohm-cm Dielectric Constant 10³ cycles Dissipation Factor 10³ cycles BOND STRENGTH: Steel to Steel Aluminum to Aluminum	0.43 Passes 550 1.1 x 10 ¹⁵ 3.11 0.02 3,000 psi 3,300 psi
Thermal Conductivity, W/m·°K Thermal Shock, MIL I 16923 Dielectric Strength V/mil Volume Resistivity, ohm-cm Dielectric Constant 10³ cycles Dissipation Factor 10³ cycles BOND STRENGTH: Steel to Steel Aluminum to Aluminum Copper to Copper	0.43 Passes 550 1.1 x 10 ¹⁵ 3.11 0.02 3,000 psi 3,300 psi 1,500 psi

PVC to PVC



Natural Rubber to Natural Rubber '

Brass to Brass 2,600 psi

Natural Rubber to Aluminum **

Teflon*to Aluminum 1,850 psi

MIX RATIO RESIN/HARDENER:

1.	Rigid formulation	100/50
2.	Semi-rigid formulation	100/100
3.	Flexible formulation	100/150

For most bonding applications, formulation #2 is used.

INSTRUCTIONS FOR USE:

- 1. By weight mix according to one of the ratios above for desired rigidity.
- 2. Degas, pour, and cure according to one of the following cure schedules:

a) 25 °C
 b) 65 °C
 c) 105 °C
 24 hours
 60 minutes
 20 minutes

PREPARATION OF SURFACES:

Surfaces must be clean and grease free. Adhesion can be substantially increased by abrading the surfaces to be bonded with emery cloth, sandpaper, carbide grinding tools, and sand blasting. A roughened, porous surface will produce the best results. Any oxidized metal films should be removed just prior to application of the epoxy adhesive mixture.

STORAGE & HANDLING:

Store both components at 25 °C in original containers. The expected shelf life is 12 months in original unopened containers.

Please read the Safety Data Sheet before using this or any other chemical.

AVAILABILITY:

These products are available in the convenient TriggerBond® dual barrel cartridges (50ml, 200ml & 400ml) and in quarts and gallons.

IMPORTANT:

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^{**}Substrate fails before bond failure

^{*}Teflon-Registered Trademark of E.I. Dupont